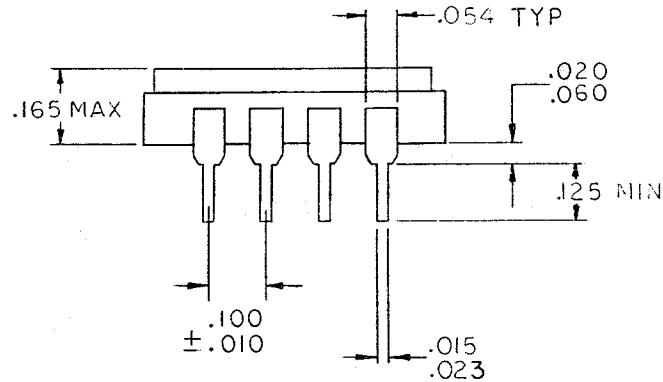
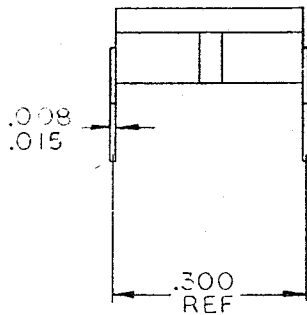
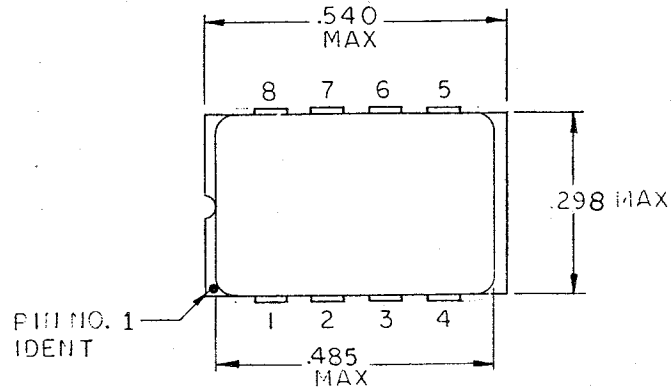


REVISIONS

REV.	SHEET	DESCRIPTION	E.C.O.	DATE	APPROVED
⊖	1	NEW DRAWING		9-12-74	R. Truittlock
A	1	REM .020 R, .110 ± .010, .485 WAS .490, .295 WAS .300, .020/.060 WAS .035 ± .010 ADDED TYP TO .054 REVISED LEAD FINISH	D-1078	4-21 75	R. Truittlock
B	1	.008/.015, .015/.023, .298 MAX WERE .008/.012, .015/.020, .295 MAX	D-1926	6/25/76	R. Truittlock
C	1	CHANGED NOTES	00041	6.27.83	Bury



LEAD FINISH TO BE ONE OF THE FOLLOWING :

1. 200  $\mu$ " MIN SOLDER MEASURED AT THE CREST OF THE FLATS .
2. 200 TO 800  $\mu$ " TIN PLATE OVER 50 TO 350  $\mu$ " NICKEL UNDERPLATE OR BASIS METAL .
3. 50 TO 100  $\mu$ " GOLD OVER 50 TO 350  $\mu$ " NICKEL UNDERPLATE .

THE LEAD FINISH, NICKEL UNDERPLATE, AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL - M - 38510E .

MIL-M-38510  
CONFIGURATION CONTROL

COMPANY PRIVATE				National Semiconductor Corporation 2900 Semiconductor Drive, Santa Clara, Calif. 95051	
DRAWN: J.MACIEL	DATE: 9-12-74	APPROVED: <i>[Signature]</i>	DATE: 9-12-74	8 LEAD HERMETIC DIP (7)	
CHECKED: <i>[Signature]</i>	DATE: 9-20-74	APPROVED: <i>[Signature]</i>	DATE: 9-20-74	B   D08C	
ENGINEER:	DATE:	RELEASED:	DATE:	SHEET 1 OF 1	REV. C